SLOVENSKI STANDARD
kSIST FprEN 16603-20-01:2014

01-oktober-2014

Vesoljska tehnika - Multipaction - Zasnova in preskušanje

Space engineering - Multipaction, design and test

Raumfahrttechnik - Multipaction-Konzeption und -Test

Systèmes sol et opérations - Conception et test prenant en compte l'effet Multipactor

Ta slovenski standard je istoveten z: **FprEN 16603-20-01**

ICS:

49.140	Vesoljski sistemi in operacije	Space systems and operations

kSIST FprEN 16603-20-01:2014 **en,fr,de**

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

FINAL DRAFT
FprEN 16603-20-01

May 2014

ICS 49.140

Will supersede EN 14777:2004

English version

Space engineering - Multipaction, design and test

Systèmes sol et opérations - Conception et test prenant en compte l'effet Multipactor

Raumfahrttechnik - Multipaction-Konzeption und -Test

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